

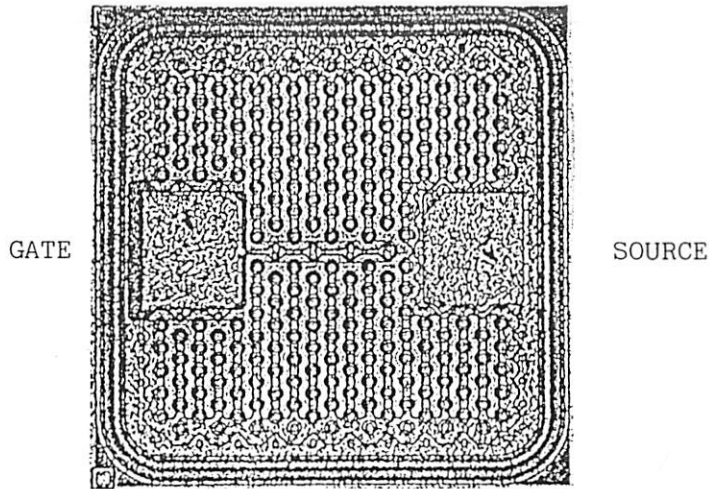


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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



CHIP BACK IS DRAIN

Topside Metal:
Backside:
Backside Potential: Drain
Mask Ref:
Bond Pads (Mils):

APPROVED BY:

MFG: Zetex

DIE SIZE (Mils): 31 X 31

THICKNESS:

DATE: 3/6/00

P/N: BSS110

DG 10.1.2
Rev A 3-4-99